

# PUSB3F96

ESD protection for ultra high-speed interfaces

Rev. 2 — 1 November 2013

Product data sheet

## 1. Product profile

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### 1.1 General description

The device is designed to protect high-speed interfaces such as SuperSpeed USB, High-Definition Multimedia Interface (HDMI), DisplayPort, external Serial Advanced Technology Attachment (eSATA) and Low Voltage Differential Signaling (LVDS) interfaces against ElectroStatic Discharge (ESD).

The device includes four high-level ESD protection diode structures for ultra high-speed signal lines and is encapsulated in a leadless small DFN2510A-10 (SOT1176-1) plastic package.

All signal lines are protected by a special diode configuration offering ultra low line capacitance of only 0.5 pF. These diodes utilize a unique snap-back structure in order to provide protection to downstream components from ESD voltages up to  $\pm 10$  kV contact exceeding IEC 61000-4-2, level 4.

### 1.2 Features and benefits

- System ESD protection for USB 2.0 and SuperSpeed USB 3.0, HDMI, DisplayPort, eSATA and LVDS
- All signal lines with integrated rail-to-rail clamping diodes for downstream ESD protection of  $\pm 10$  kV exceeding IEC 61000-4-2, level 4
- Matched 0.5 mm trace spacing
- Signal lines with  $\leq 0.05$  pF matching capacitance between signal pairs
- Line capacitance of only 0.5 pF for each channel
- Design-friendly 'pass-through' signal routing

### 1.3 Applications

The device is designed for high-speed receiver and transmitter port protection:

- TVs and monitors
- DVD recorders and players
- Notebooks, main board graphic cards and ports
- Set-top boxes and game consoles



## 2. Pinning information

Table 1. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	CH1	channel 1 ESD protection		
2	CH2	channel 2 ESD protection		
3	GND	ground		
4	CH3	channel 3 ESD protection		
5	CH4	channel 4 ESD protection		
6	n.c.	not connected		
7	n.c.	not connected		
8	GND	ground		
9	n.c.	not connected		
10	n.c.	not connected		

## 3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
PUSB3F96	DFN2510A-10	plastic extremely thin small outline package; no leads; 10 terminals; body 1 × 2.5 × 0.5 mm	SOT1176-1

## 4. Marking

Table 3. Marking codes

Type number	Marking code
PUSB3F96	96

## 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_I$	input voltage		-0.5	+5.5	V
$V_{ESD}$	electrostatic discharge voltage	IEC 61000-4-2, level 4 [1]			
		contact discharge	-10	+10	kV
		air discharge	-15	+15	kV
$T_{amb}$	ambient temperature		-40	+85	°C
$T_{stg}$	storage temperature		-55	+125	°C

[1] All pins to ground.

## 6. Characteristics

**Table 5. Characteristics**

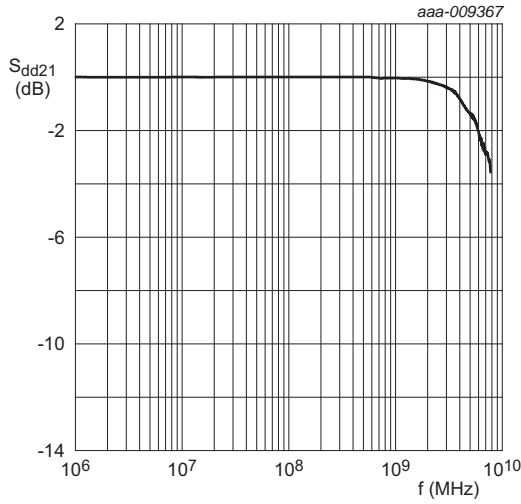
$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{BR}$	breakdown voltage	$I_I = 1\text{ mA}$	6	-	-	V
$I_{LR}$	reverse leakage current	per channel; $V_I = 3\text{ V}$	-	-	1	$\mu\text{A}$
$V_F$	forward voltage	$I_I = 1\text{ mA}$	-	0.7	-	V
$C_{line}$	line capacitance	$f = 1\text{ MHz}$ ; $V_I = 3.3\text{ V}$	[1] -	0.5	0.6	pF
$\Delta C_{line}$	line capacitance difference	$f = 1\text{ MHz}$ ; $V_I = 3.3\text{ V}$	[1] -	0.05	-	pF
$r_{dyn}$	dynamic resistance	surge	[2]			
		positive transient	-	0.41	-	$\Omega$
		negative transient	-	0.26	-	$\Omega$
		TLP	[3]			
		positive transient	-	0.43	-	$\Omega$
		negative transient	-	0.28	-	$\Omega$
$V_{CL}$	clamping voltage	$I_{PP} = 5.2\text{ A}$	[2]			
		positive transient	-	4.6	-	V
		$I_{PP} = -4.4\text{ A}$	[2]			
		negative transient	-	-2.2	-	V

[1] This parameter is guaranteed by design.

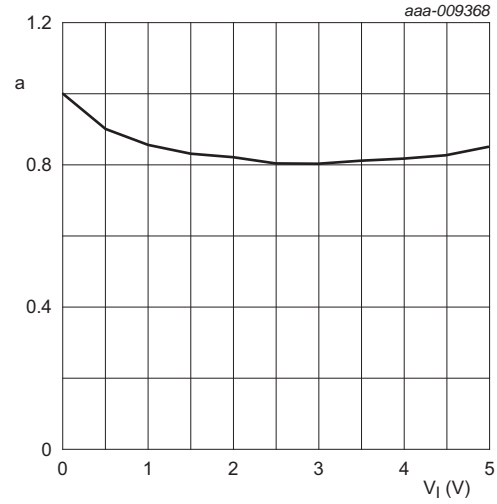
[2] According to IEC 61000-4-5 (8/20  $\mu\text{s}$  current waveform).

[3] 100 ns Transmission Line Pulse (TLP); 50  $\Omega$ ; pulser at 80 ns.



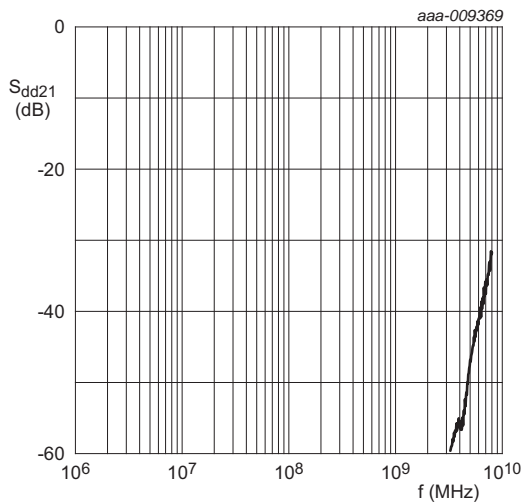
differential mode

Fig 1. Insertion loss; typical values



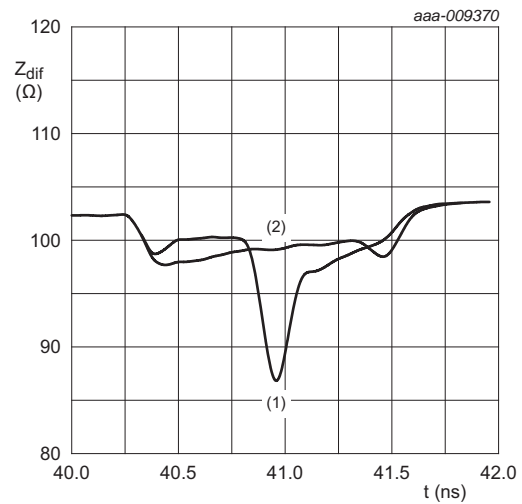
$$a = \frac{C_{line}}{C_{line}(V_I = 0 \text{ V})}$$

Fig 2. Relative capacitance as a function of input voltage; typical values



Sdd21 normalized to 100 Ω;  
differential pairs CH1/CH2 versus CH3/CH4

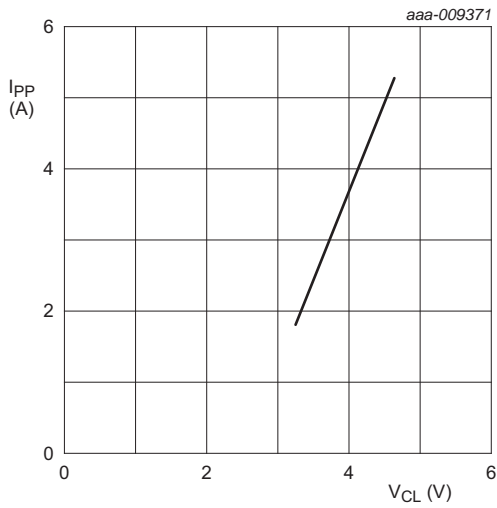
Fig 3. Crosstalk; typical values



$t_r = 200 \text{ ps}$ ; differential pair CH1 + CH2

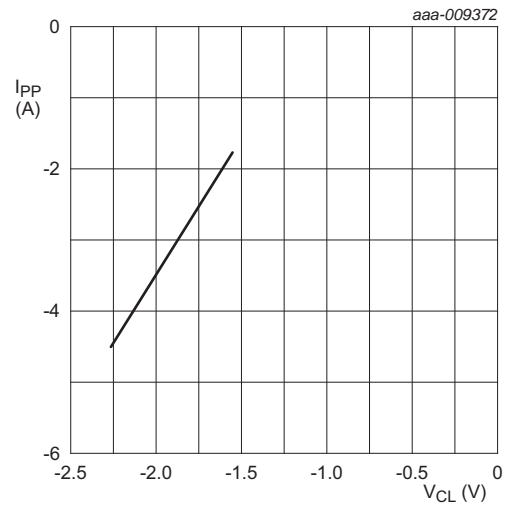
- (1) PUSB3F96 on reference board
- (2) Reference board without device under test (DUT)

Fig 4. Differential Time Domain Reflectometer (TDR) plot; typical values



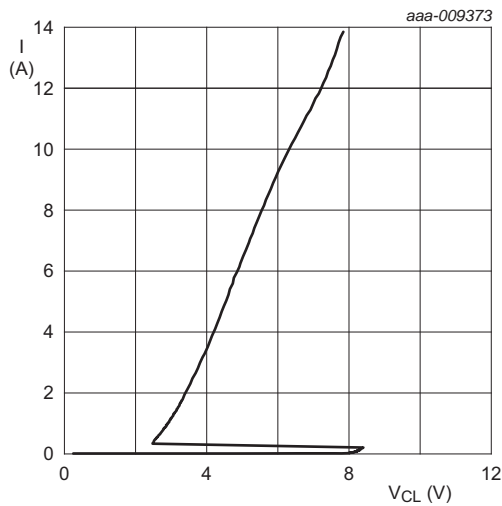
IEC 61000-4-5;  $t_p = 8/20 \mu s$ ; positive pulse

**Fig 5. Dynamic resistance with positive clamping; typical values**



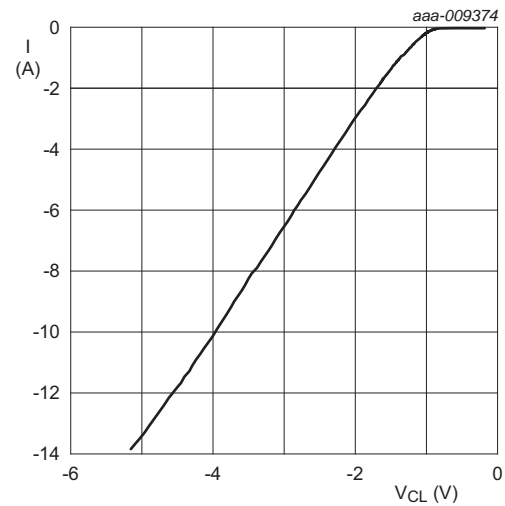
IEC 61000-4-5;  $t_p = 8/20 \mu s$ ; negative pulse

**Fig 6. Dynamic resistance with negative clamping; typical values**



$t_p = 100 ns$ ; Transmission Line Pulse (TLP)

**Fig 7. Dynamic resistance with positive clamping; typical values**



$t_p = 100 ns$ ; Transmission Line Pulse (TLP)

**Fig 8. Dynamic resistance with negative clamping; typical values**

The device uses an advanced clamping structure showing a negative dynamic resistance. This snap-back behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snap-back state after exceeding breakdown voltage (due to an ESD pulse for instance).

## 7. Application information

The device is designed to provide high-level ESD protection for high-speed serial data buses such as HDMI, DisplayPort, eSATA and LVDS data lines.

When designing the Printed-Circuit Board (PCB), give careful consideration to impedance matching and signal coupling. Do not connect the signal lines to unlimited current sources like, for example, a battery.

A basic application diagram for the ESD protection of an HDMI interface is shown in [Figure 9](#).

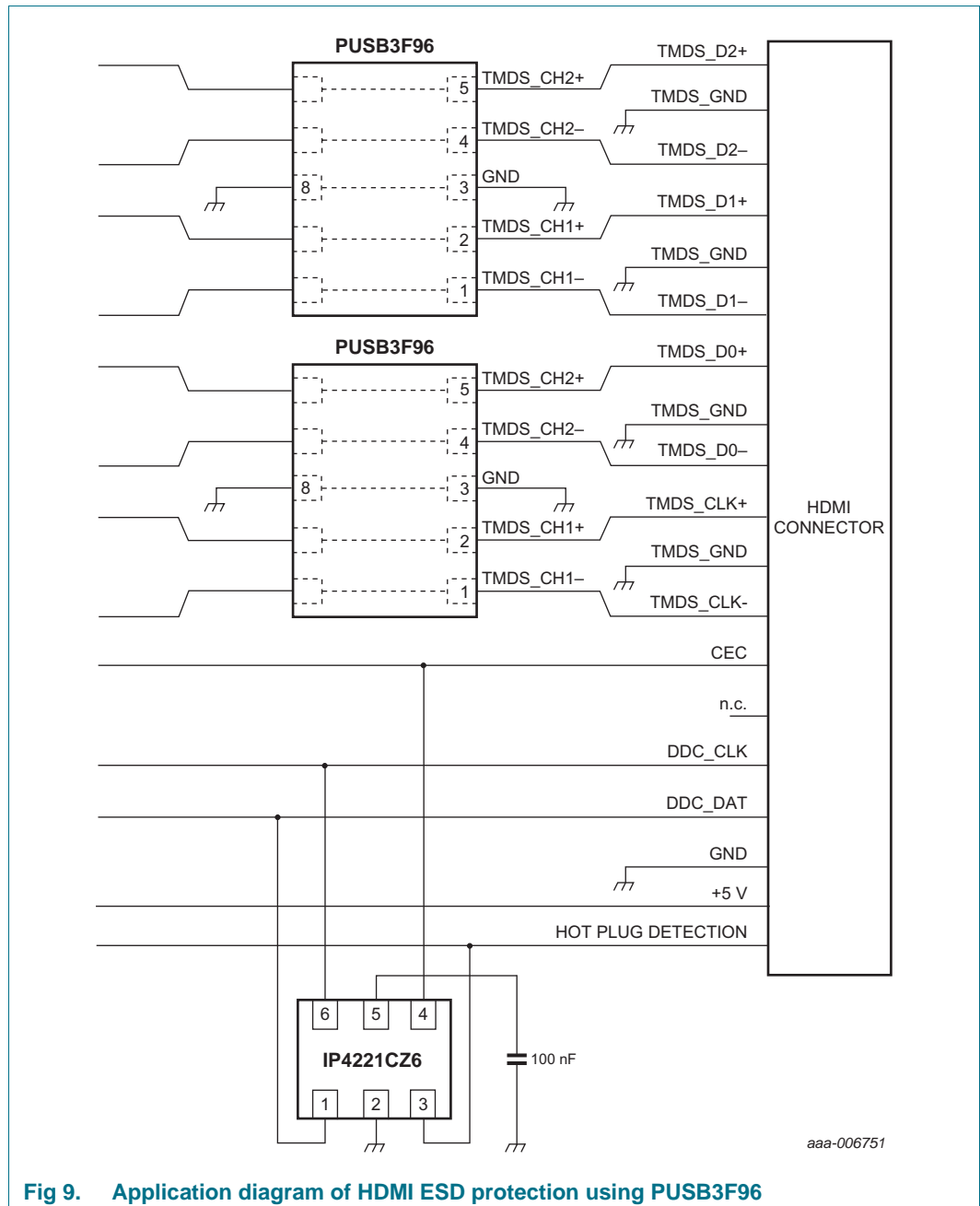


Fig 9. Application diagram of HDMI ESD protection using PUSB3F96

## 8. Package outline

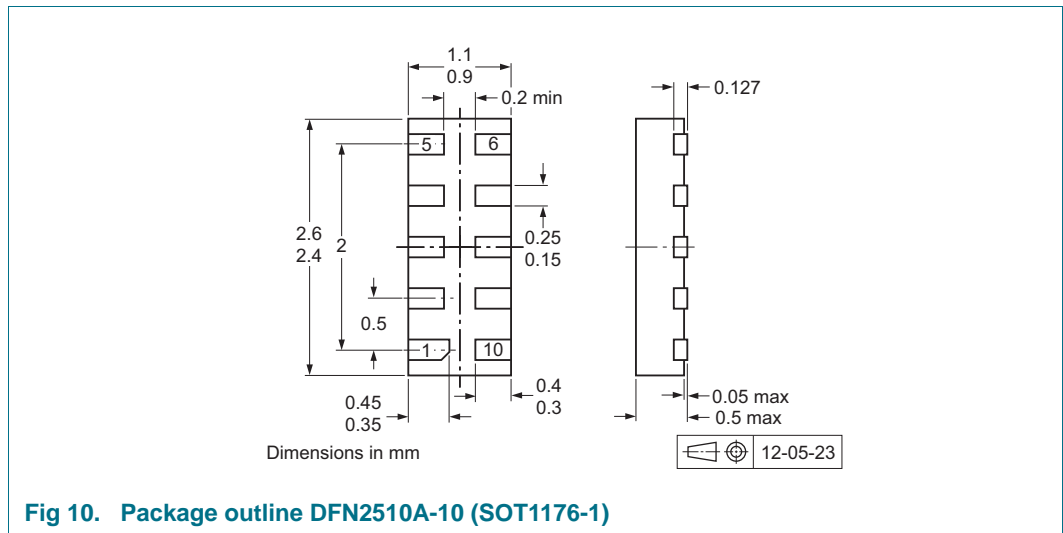


Fig 10. Package outline DFN2510A-10 (SOT1176-1)

## 9. Soldering

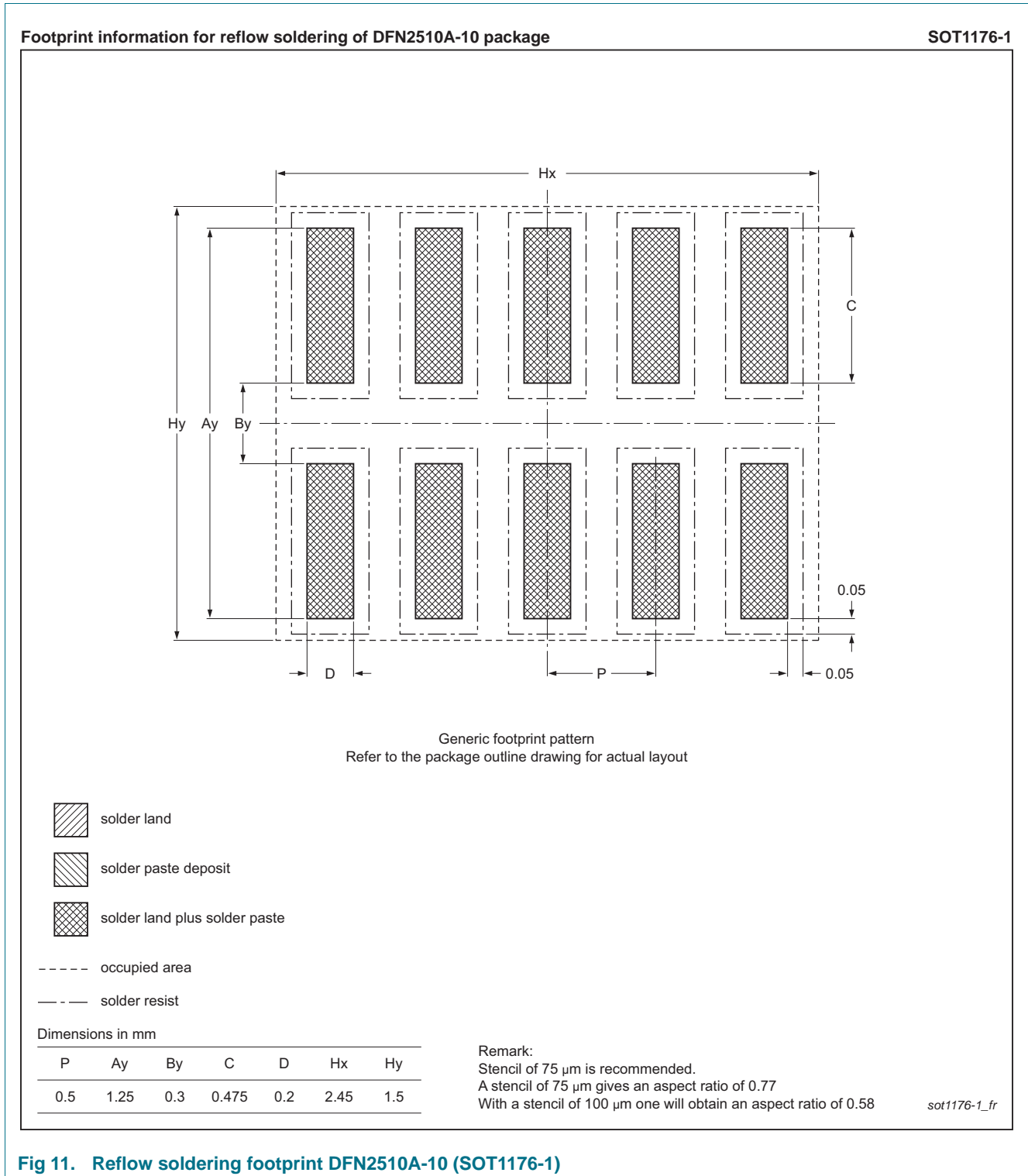


Fig 11. Reflow soldering footprint DFN2510A-10 (SOT1176-1)



## 10. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PUSB3F96 v.2	20131101	Product data sheet	-	PUSB3F96 v.1
Modifications:	• Measurements and characteristics updated after product characterization.			
PUSB3F96 v.1	20130226	Product data sheet	-	-

## 11. Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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